

SID

Factory: Rot am See

Article:

549

ML8

Provided:

Kracht, Enrico

Customer:

Date:

29.09.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	250		2		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3		
		18	L2			
A-RS-FR4-ML-0.25mm-018+018-TG150-HF	50200928	254		4	A01	
		18	L3			
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	240		5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6		
		18	L4			
A-RS-FR4-ML-0.25mm-018+018-TG150-HF	50200928	254		7	A02	B00
		18	L5			
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	240		8		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		9		
		18	L6			
A-RS-FR4-ML-0.25mm-018+018-TG150-HF	50200928	254		10	A03	
		18	L7			
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	250		11		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		12		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13		

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1886 µm

Version 1.2.14.15

© Würth Elektronik